EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	10	((solder$3 or bump$3 or braz$3) near5 (bond$3 near5 (stage or station)) near5 (temperature or heat$3 or reflow$3 or melt$3 or cool$3 or solidification or solidif$3) near5 (sens$3 or sensor or control or control$4))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/22 11:39
L2	24	((solder$3 or bump$3 or braz$3) with (bond$3 near5 (stage or station)) with (temperature or heat$3 or reflow$3 or melt$3 or cool$3 or solidification or solidif$3) with (sens$3 or sensor or control or control$4))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/22 11:31
L5	4962	(228/1.1,8,9,110.1,180.21, 180.22,49.5,48,49.1,49.2). ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 11:54
L6	7239	(438/108,613,106,612). ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 11:54
L7	629	29/25.01.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 11:54
L8	18	5 and ((solder$3 or bump$3 or braz$3) same (bond$3 near5 (stage or station)) same (temperature or heat$3 or reflow$3 or melt$3 or cool$3 or solidification or solidif$3) same(sens$3 or sensor or control or control$4))	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 11:44

L9	11	6 and ((solder$3 or bump$3 or braz$3) same (bond$3 near5 (stage or station)) same (temperature or heat$3 or reflow$3 or melt$3 or cool$3 or solidification or solidif$3) same(sens$3 or sensor or control or control$4))	US-PGP UB; USPAT; USOCR	OR	ON	2008/01/22 11:46
L10	1	7 and ((solder$3 or bump$3 or braz$3) same (bond$3 near5 (stage or station)) same (temperature or heat$3 or reflow$3 or melt$3 or cool$3 or solidification or solidif$3) same(sens$3 or sensor or control or control$4))	US-PGP UB; USPAT; USOCR	OR	ON	2008/01/22 11:59
L20	1341	(228/1.1,8,9,110.1,180.21, 180.22,49.5,48,49.1,49.2). ccls.	EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2008/01/22 11:55
L21	2091	(438/108,613,106,612). ccls.	EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2008/01/22 11:54
L22	1645	29/25.01.ccls.	EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2008/01/22 11:54
L23	5060	20 or 21 or 22	EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2008/01/22 11:55

L28	1	23 and ((solder$3 or bump$3 or braz$3) and (bond$3 same (stage or station)) and (temperature or heat$3 or reflow$3 or melt$3 or cool$3 or solidification or solidif$3) and (sens$3 or sensor or control or control$4))	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/22 12:01
L29	12577	5 or 6 or 7	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 12:01
L30	75	29 and ((bump same (station or platform or bench or support$3 or stage or head)) and ((load or wafer or workpiece or component or part or specimen or element) same (transfer$4 or carrier or transport$3 or convey$3 or conveyor or conveyance)) same (control or control$4 or controllable or controllably or sens$3 or sensor or regulat$3 or monitor$3) same (heat$3 or temperature or reflow$3 or cool$4 or melt$3 or "pre-heat" or "pre-heating" or (pre near5 heat$3) or "post-heat" or "post-heating" or (post near5 heat$3) or ((pre or post) with (form$3 or formation))))	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 12:46

L31	0	23 and ((bump same (station or platform or bench or support$3 or stage)) and ((load or wafer or workpiece or component or part or specimen or element) same (transfer$4 or carrier or transport$3 or convey$3 or conveyor or conveyance or (carry$3 near5 (in or out)))) same (control or control$4 or controllable or controllably or sens$3 or sensor or regulat$3 or monitor$3) same (heat$3 or temperature or cool$4 or "pre-heat" or "pre-heating" or (pre near5 heat$3) or "post-heat" or "post-heating" or (post near5 heat$3) or ((pre or post) with (form$3 or formation))))	EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2008/01/22 12:50

L32	15	((bump same (station or platform or bench or support$3 or stage)) and ((load or wafer or workpiece or component or part or specimen or element) same (transfer$4 or carrier or transport$3 or convey$3 or conveyor or conveyance or (carry$3 near5 (in or out)))) same (control or control$4 or controllable or controllably or sens$3 or sensor or regulat$3 or monitor$3) same (heat$3 or temperature or cool$4 or "pre-heat" or "pre-heating" or (pre near5 heat$3) or "post-heat" or "post-heating" or (post near5 heat$3) or ((pre or post) with (form$3 or formation))))	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/22 12:54
L33	649	((bump same (station or platform or bench or support$3 or stage)) and ((load or wafer or workpiece or component or part or specimen or element) same (transfer$4 or carrier or transport$3 or convey$3 or conveyor or conveyance or (carry$3 near5 (in or out)))) same (control or control$4 or controllable or controllably or sens$3 or sensor or regulat$3 or monitor$3) same (heat$3 or temperature or cool$4 or "pre-heat" or "pre-heating" or (pre near5 heat$3) or "post-heat" or "post-heating" or (post near5 heat$3) or ((pre or post) with (form$3 or formation))))	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 13:18

EAST Search History

L34	1	("5878942").PN.	USPAT; USOCR	OR	OFF	2008/01/22 12:57
L35	1	("6787391").PN.	USPAT; USOCR	OR	OFF	2008/01/22 12:57
L36	141	33 and (warp$3 or buckl$3 or (thermal near5 deform$3) or crack$3 or (pyroelectric near5 effect))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/22 13:27
L37	75	((bump near5 (station or platform or bench or support$3 or stage)) near5 (wafer or silicon or quartz or semiconductor chip) near5 (heat$3 or temperature or cool$4 or "pre-heat" or "pre-heating" or (pre near5 heat$3) or "post-heat" or "post-heating" or (post near5 heat$3) or ((pre or post) near2 (form$3 or formation)) near5 (speed or rate)))	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/22 13:31
L38	33	37 and (warp$3 or buckl$3 or (thermal near5 deform$3) or crack$3 or (pyroelectric near5 effect))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/22 13:31

L39	19	((bump near5 (station or platform or bench or support$3 or stage)) near5 (wafer or silicon or quartz or semiconductor chip) near5 (heat$3 or temperature or cool$4 or "pre-heat" or "pre-heating" or (pre near5 heat$3) or "post-heat" or "post-heating" or (post near5 heat$3) or ((pre or post) near2 (form$3 or formation)) near5 (speed or rate)))	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/22 13:53
L40	1	39 and (warp$3 or buckl$3 or (thermal near5 deform$3) or crack$3 or (pyroelectric near5 effect))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/22 13:46
L42	15	(wafer near5 bump$3 near5 ((pre or post) near5 (heat$3 or aneal$3)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/22 13:46
L43	80	(bump$3 near5 ((pre or post) near5 (heat$3 or aneal$3)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/22 13:48

L44	26	43 and (warp$3 or buckl$3 or (thermal near5 deform$3) or crack$3 or (pyroelectric near5 effect))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/22 13:48
L45	1192	((solder$3 or braz$3) near5 ((pre or post) near5 (heat$3 or aneal$3)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/22 13:48
L46	230	45 and (warp$3 or buckl$3 or (thermal near5 deform$3) or crack$3 or (pyroelectric near5 effect))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/22 13:50
L47	156	46 and ((temperature or cool$4 or heat$3) same (control or control$4 or controllably or controllable or sens$3 or sensor or speed or rate or regulat$3 or monitor$3))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/22 13:52
L49	106	47 and (station or platform or bench or support$3 or stage)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/22 13:54